| L Number | Hits | Search Text | DB | Time stamp |
|-------------|--------|--|---|---------------------|
| 1 | 346691 | wafer | USPAT; US-PGPUB; EPO; JPO; | 2004/04/03 17:42 |
| 2 | 9070 | removing near photoresist | DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:42 |
| 3 | 3622 | wafer and (removing near photoresist) | IBM_TDB USPAT; US-PGPUB; EPO; JPO; | 2004/04/03 17:42 |
| 4 | 20550 | process near chamber | DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:42 |
| 5 | 18592 | wafer near (stage or support) | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:43 |
| 6 | 186 | (wafer and (removing near photoresist)) and (process near chamber) | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:43 |
| 7 | 38 | <pre>(wafer near (stage or support)) and ((wafer and (removing near photoresist)) and (process near chamber))</pre> | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/03 17:43 |
| 9 | 0 | ((wafer near (stage or support)) and ((wafer and (removing near photoresist)) and (process near chamber))) and (heating near temperature near "210") | USPAT; US-PGPUB; | 2004/04/03 17:43 |
| 8 | 12 | heating near temperature near "210" | USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:45 |
| 10 | 104398 | heating near temperature | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/03 17:45 |
| 11 | 0 | ((wafer near (stage or support)) and ((wafer and (removing near photoresist)) and (process near chamber))) and (heating near temperature) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2004/04/03 17:45 |
| 12 | 6204 | wafer and (heating near temperature) | USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2004/04/03 17:45 |
| 13 | 123 | (removing near photoresist) and (wafer and (heating near temperature)) | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/03 17:45 |

| 14 | 5 | (process near chamber) and ((removing | USPAT; | 2004/04/03 |
|----------|--------|---|-----------|------------|
| | | near photoresist) and (wafer and (heating | US-PGPUB; | 17:56 |
| | | near temperature))) | EPO; JPO; | |
| | | lieur comporadaro,,, | DERWENT; | |
| | | | IBM TDB | |
| 15 | 382588 | plasma | USPAT; | 2004/04/03 |
| | 302000 | prasma | US-PGPUB; | 17:56 |
| | | | EPO; JPO; | 17.30 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 16 | 74 | ((removing near photoresist) and (wafer | USPAT; | 2004/04/03 |
| 10 | , , | and (heating near temperature))) and | US-PGPUB; | 17:57 |
| | | plasma | EPO; JPO; | 17.37 |
| | | prasma | DERWENT; | |
| | | | IBM TDB | |
| 17 | 117296 | 219/\$.ccls. | USPAT; | 2004/04/03 |
| + ' | 11/250 | 2137 Q. CC13. | US-PGPUB; | 17:57 |
| | | | EPO; JPO; | 17.37 |
| | | | DERWENT; | |
| | | | IBM TDB | · |
| 18 | 1 | (((removing near photoresist) and (wafer | USPAT; | 2004/04/03 |
| 10 | 1 | and (heating near temperature))) and | US-PGPUB; | 17:59 |
| | | plasma) and 219/\$.ccls. | EPO; JPO; | 17.59 |
| <u> </u> | | prasma, and 219/9.ccrs. | DERWENT; | |
| | | | IBM TDB | |
| 19 | 21 | wafer and (removing near photoresist) and | USPAT; | 2004/04/03 |
| 19 | 21 | plasma and 219/\$.ccls. | US-PGPUB; | 18:01 |
| | | prasma and 213/ V. CC13. | EPO; JPO; | 10:01 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 20 | 927645 | heating and temperature | USPAT; | 2004/04/03 |
| | J27043 | licacting and competatore | US-PGPUB; | 18:01 |
| | | | EPO; JPO; | 10.01 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| 21 | 14 | (wafer and (removing near photoresist) | USPAT; | 2004/04/03 |
| 6 I | 14 | and plasma and 219/\$.ccls.) and (heating | US-PGPUB; | 18:01 |
| | | and temperature) | EPO; JPO; | 10.01 |
| | | | DERWENT; | |
| | | | IBM TDB | |
| L | | <u> </u> | TOLI TOD | <u> </u> |